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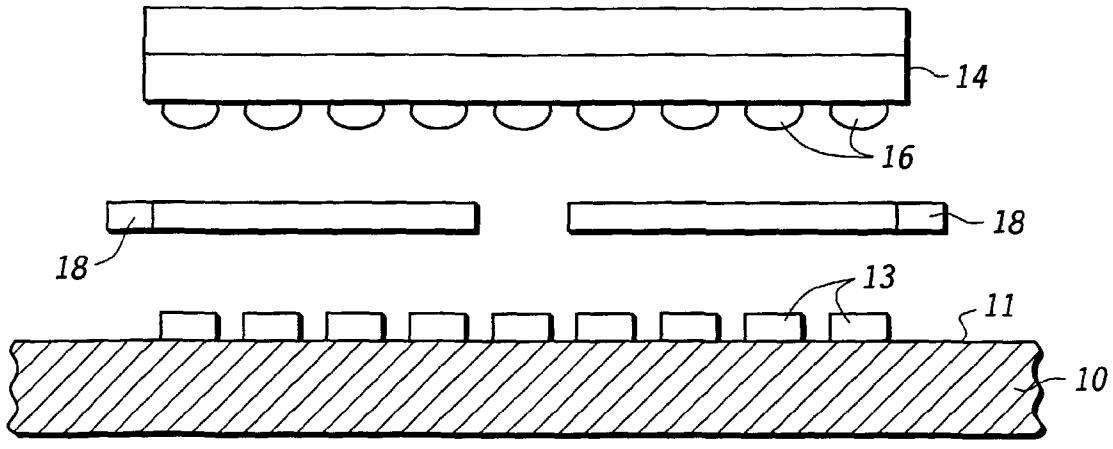
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(54) Title: UNDERFILL FILM FOR PRINTED WIRING ASSEMBLIES



(57) Abstract: A self supported underfill film (18) adhesively bonds surface mount integrated circuit packages (14) to a printed circuit board (10). The printed circuit board has conductive traces (12) and exposed conductive pads (13) on the surface. A film adhesive is strategically positioned on the printed circuit board near the conductive pads, and the surface mount integrated circuit package is then placed on the board so that the conductive pads (16) on the package align with the conductive pads on the board. The film adhesive softens when the package is soldered to the board, and the film ultimately serves as an underfill to increase the mechanical integrity of the solder joints.

WO 2004/071140 A3